# **10-Bit Bus Switch**

The ON Semiconductor 74FST3861 is a 10–bit, high performance bus switch. The device is CMOS TTL compatible when operating between 4 and 5.5 Volts. The device exhibits extremely low  $R_{ON}$  and adds nearly zero propagation delay. The device adds no noise or ground bounce to the system.

- $R_{ON} < 4 \Omega$  Typical
- Less Than 0.25 ns–Max Delay Through Switch
- Nearly Zero Standby Current
- No Circuit Bounce
- Control Inputs are TTL/CMOS Compatible
- Pin–For–Pin Compatible With QS3861, FST3861, CBT3861
- All Popular Packages: SOIC-24, TSSOP-24, QSOP-24

			-
	1	24	
	2	23	
$A_2 \blacksquare$	3	22	<b>⊐</b> В1
$A_3 \square$	4	21	
$A_4 \square$	5	20	<b>—</b> В <sub>3</sub>
$A_5 \square$	6	19	ро В <sub>4</sub>
$A_6 =$	7	18	
A7 📼	8	17	
$A_8 \square$	9	16	
$A_9 \blacksquare$	10	15	
A <sub>10</sub> 🗖	11	14	но В <sub>9</sub>
	12	13	Б В <sub>10</sub>

TRUTH 1	TABLE
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Input	
OE	Operation
L	A Port = B Port
н	Disconnect

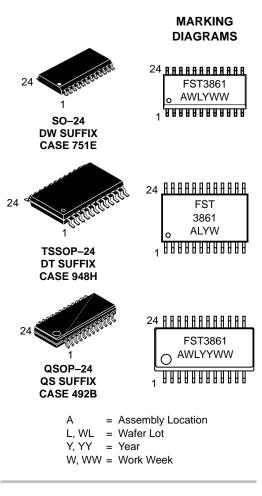
NOTE:

H = HIGH Voltage Level L = LOW Voltage Level



# **ON Semiconductor®**

http://onsemi.com



#### **ORDERING INFORMATION**

Device	Package	Shipping			
74FST3861DW	SO-24	48 Units/Rail			
74FST3861DWR2	SO-24	2500 Units/Reel			
74FST3861DT	TSSOP-24	96 Units/Rail			
74FST3861DTR2	TSSOP-24	2500 Units/Reel			
74FST3861QS	QSOP-24	96 Units/Rail			
74FST3861QSR	QSOP-24	2500 Units/Reel			

Figure 1. 24–Lead Pinout

SO24-7/SO24-8/SO24-9

### PIN NAMES

Pin	Description
ŌĒ	Bus Switch Enables
NC	No Connect
A <sub>1</sub> to A <sub>10</sub>	Bus A
B <sub>1</sub> to B <sub>10</sub>	Bus B



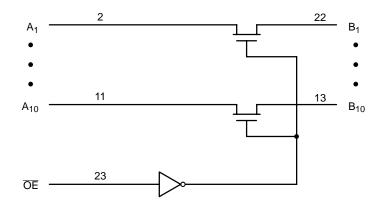


Figure 2. Logic Diagram

## MAXIMUM RATINGS

Symbol	Pa	rameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage		-0.5 to $+7.0$	V
VI	DC Input Voltage		-0.5 to +7.0	V
V <sub>O</sub>	DC Output Voltage		-0.5 to +7.0	V
I <sub>IK</sub>	DC Input Diode Current	$V_{I} < GND$	-50	mA
I <sub>OK</sub>	DC Output Diode Current	$V_{O} < GND$	-50	mA
Ι <sub>Ο</sub>	DC Output Sink Current		128	mA
I <sub>CC</sub>	DC Supply Current per Supply Pin		±100	mA
I <sub>GND</sub>	DC Ground Current per Ground Pin		±100	mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C	
TL	Lead Temperature, 1 mm from Case fo	r 10 Seconds	260	°C
TJ	Junction Temperature Under Bias		+ 150	°C
$\theta_{JA}$	Thermal Resistance	SOIC TSSOP QSOP	125 170 200	°C/W
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V–0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage	Human Body Model (Note 1) Machine Model (Note 2) Charged Device Model (Note 3)	>2000 >200 N/A	V
I <sub>LATCH-UP</sub>	Latch–Up Performance	Above $V_{CC}$ and Below GND at 85°C (Note 4)	±500	mA

Maximum Ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum–rated conditions is not implied. Functional operation should be restricted to the Recommended Operating Conditions.

1. Tested to EIA/JESD22–A114–A.

2. Tested to EIA/JESD22-A115-A.

3. Tested to JESD22-C101-A.

4. Tested to EIA/JESD78.

### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Р	Parameter			Unit
V <sub>CC</sub>	Supply Voltage	Operating, Data Retention Only	4.0	5.5	V
VI	Input Voltage	(Note 5)	0	5.5	V
Vo	Output Voltage	(HIGH or LOW State)	0	5.5	V
T <sub>A</sub>	Operating Free–Air Temperature		-40	+ 85	°C
$\Delta t / \Delta V$	Input Transition Rise or Fall Rate Switch I/O	Switch Control Input V <sub>CC</sub> = 5.0 V $\pm$ 0.5 V	0	DC 5	ns/V

5. Unused control inputs may not be left open. All control inputs must be tied to a high or low logic input voltage level.

## DC ELECTRICAL CHARACTERISTICS

			Vcc	T <sub>A</sub> = -	40°C to	+85°C	
Symbol	Parameter	Conditions	(V)	Min	Тур*	Мах	Unit
V <sub>IK</sub>	Clamp Diode Resistance	$I_{IN} = -18mA$	4.5			- 1.2	V
V <sub>IH</sub>	High–Level Input Voltage		4.0 to 5.5	2.0			V
V <sub>IL</sub>	Low-Level Input Voltage		4.0 to 5.5			0.8	V
I <sub>I</sub>	Input Leakage Current	$0 \le V_{IN} \le 5.5 V$	5.5			±1.0	μΑ
I <sub>OZ</sub>	OFF-STATE Leakage Current	$0 \le A, B \le V_{CC}$	5.5			±1.0	μΑ
R <sub>ON</sub>	Switch On Resistance (Note 6)	$V_{IN} = 0 V$ , $I_{IN} = 64 mA$	4.5		4	7	Ω
		$V_{IN} = 0 \text{ V}, I_{IN} = 30 \text{ mA}$	4.5		4	7	
		V <sub>IN</sub> = 2.4 V, I <sub>IN</sub> = 15 mA	4.5		8	15	
		V <sub>IN</sub> = 2.4 V, I <sub>IN</sub> = 15 mA	4.0		11	20	
I <sub>CC</sub>	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND, $I_{OUT} = 0$	5.5			3	μΑ
$\Delta I_{CC}$	Increase In I <sub>CC</sub> per Input	One input at 3.4 V, Other inputs at $V_{CC}$ or GND	5.5			2.5	mA

\*Typical values are at V<sub>CC</sub> = 5.0 V and T<sub>A</sub> = 25°C.
6. Measured by the voltage drop between A and B pins at the indicated current through the switch. On resistance is determined by the lower of the voltages on the two (A or B) pins.

## **AC ELECTRICAL CHARACTERISTICS**

			$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$ $C_L = 50 \text{ pF, RU} = \text{RD} = 500 \Omega$		<b>)</b> Ω		
			$V_{CC} = 4$	.5–5.5 V	V <sub>CC</sub> =	4.0 V	
Symbol	Parameter	Conditions	Min	Max	Min	Max	Unit
t <sub>PHL</sub> , t <sub>PLH</sub>	Prop Delay Bus to Bus (Note 7)	V <sub>I</sub> = OPEN		0.25		0.25	ns
t <sub>PZH</sub> , t <sub>PZL</sub>	Output Enable Time, I <sub>OE</sub> to Bus A, B	$V_I = OPEN$ for $t_{PZH}$	1.0	5.1		5.6	ns
t <sub>PHZ</sub> , t <sub>PLZ</sub>	Output Disable Time, I <sub>OE</sub> to Bus A, B	$V_I = OPEN$ for $t_{PHZ}$	1.0	5.5		5.5	ns

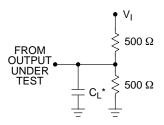
This parameter is guaranteed by design but is not tested. The bus switch contributes no propagation delay other than the RC delay of the typical On resistance of the switch and the 50 pF load capacitance, when driven by an ideal voltage source (zero output impedance).

## **CAPACITANCE** (Note 8)

Symbol	Parameter	Conditions	Тур	Max	Unit
C <sub>IN</sub>	Control Pin Input Capacitance	V <sub>CC</sub> = 5.0 V	3		pF
C <sub>I/O</sub>	A/B Port Input/Output Capacitance	$V_{CC}, \overline{OE} = 5.0 V$	5		pF

8.  $T_A = +25^{\circ}C$ , f = 1 MHz, Capacitance is characterized but not tested.

#### AC Loading and Waveforms

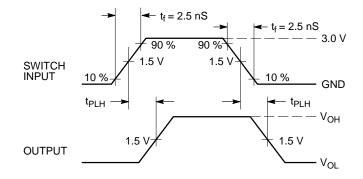


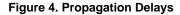
#### NOTES:

1. Input driven by 50  $\Omega$  source terminated in 50  $\Omega.$  2. CL includes load and stray capacitance.

 $^{*}C_{L} = 50 \text{ pF}$ 

#### Figure 3. AC Test Circuit





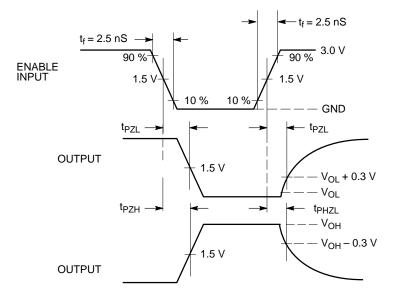
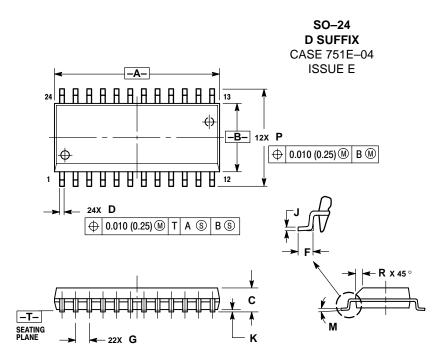


Figure 5. Enable/Disable Delays

# PACKAGE DIMENSIONS



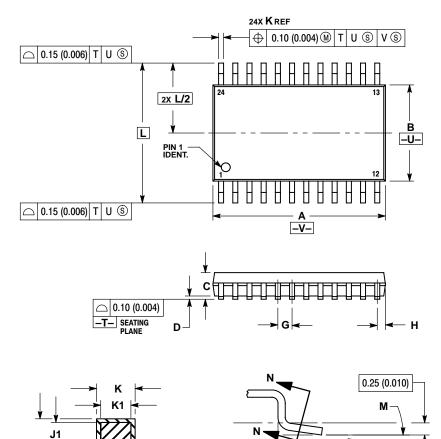
NOTES:

- NOTES:
   DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: MILLIMETER.
   DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
   MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
   DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	15.25	15.54	0.601	0.612	
В	7.40	7.60	0.292	0.299	
C	2.35	2.65	0.093	0.104	
D	0.35	0.49	0.014	0.019	
F	0.41	0.90	0.016	0.035	
G	1.27	BSC	0.050	BSC	
J	0.23	0.32	0.009	0.013	
K	0.13	0.29	0.005	0.011	
Μ	0 °	8°	0 °	8 °	
Ρ	10.05	10.55	0.395	0.415	
R	0.25	0.75	0.010	0.029	

## PACKAGE DIMENSIONS

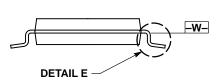
TSSOP-24 DT SUFFIX CASE 948H-01 **ISSUE A** 



SECTION N-N

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006)
- 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED
  2.35 (2010) PEP SIDE
- PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE. 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	7.70	7.90	0.303	0.311
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026	BSC
Н	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40		0.252 BSC	
Μ	0 °	8°	0°	8°

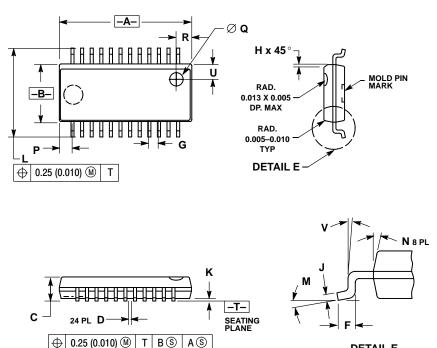


F

DETAIL E

#### PACKAGE DIMENSIONS

QSOP-24 **QS SUFFIX** CASE 492B-01 ISSUE O



DETAIL E

NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH. THE BOTTOM PACKAGE SHALL BE BIGGER THAN 2. 3. THE TOP PACKAGE BY 4 MILS (NOTE: LEAD SIDE ONLY). BOTTOM PACKAGE DIMENSION SHALL FOLLOW THE DIMENSION STATED IN THIS
- DRAWING. PLASTIC DIMENSIONS DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR 4 PROTRUSIONS SHALL NOT EXCEED 6 MILS PER
- SIDE 5.
- BOTTOM EJECTOR PIN WILL INCLUDE THE COUNTRY OF ORIGIN (COO) AND MOLD CAVITY I.D.

		`	'	
	INCHES		MILLIMETERS	
DIM	MAX	MIN	MAX	MIN
Α	0.337	0.344	8.56	8.74
В	0.150	0.157	3.81	3.99
C	0.061	0.068	1.55	1.73
D	0.008	0.012	0.20	0.31
F	0.016	0.035	0.41	0.89
G	0.025 BSC		0.64 BSC	
Н	0.008	0.018	0.20	0.46
J	0.0098	0.0075	0.249	0.191
K	0.004	0.010	0.10	0.25
L	0.230	0.244	5.84	6.20
М	0 °	8 °	0 °	8°
Ν	0°	7°	0 °	7 °
Р	0.027	0.037	0.69	0.94
Q	0.035 DIA		0.89 DIA	
R	0.035	0.045	0.89	1.14
U	0.035	0.045	0.89	1.14
۷	0 °	8 °	0 °	8 °

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